



SOD106

transfer-moulded thermo-setting plastic small rectangular surface mounted package; 2 connectors

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SMA; PMOS
Package type industry code	SMA; PMOS
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	DO-214AC
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.3	-	4.4	4.5	mm
E	package width	2.4	-	2.6	2.8	mm
A	seated height	2	-	2.15	2.3	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

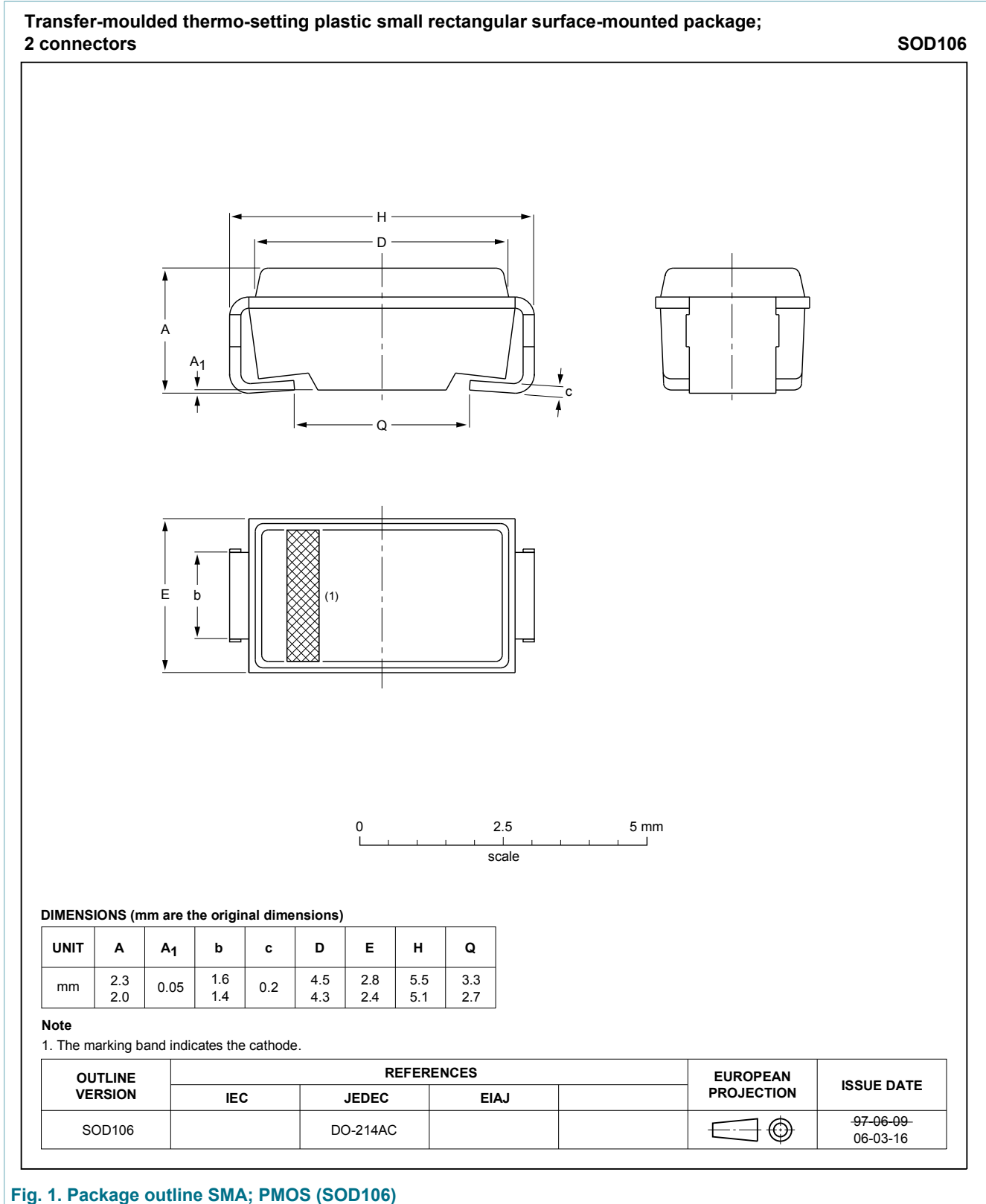


Fig. 1. Package outline SMA; PMOS (SOD106)

3. Soldering

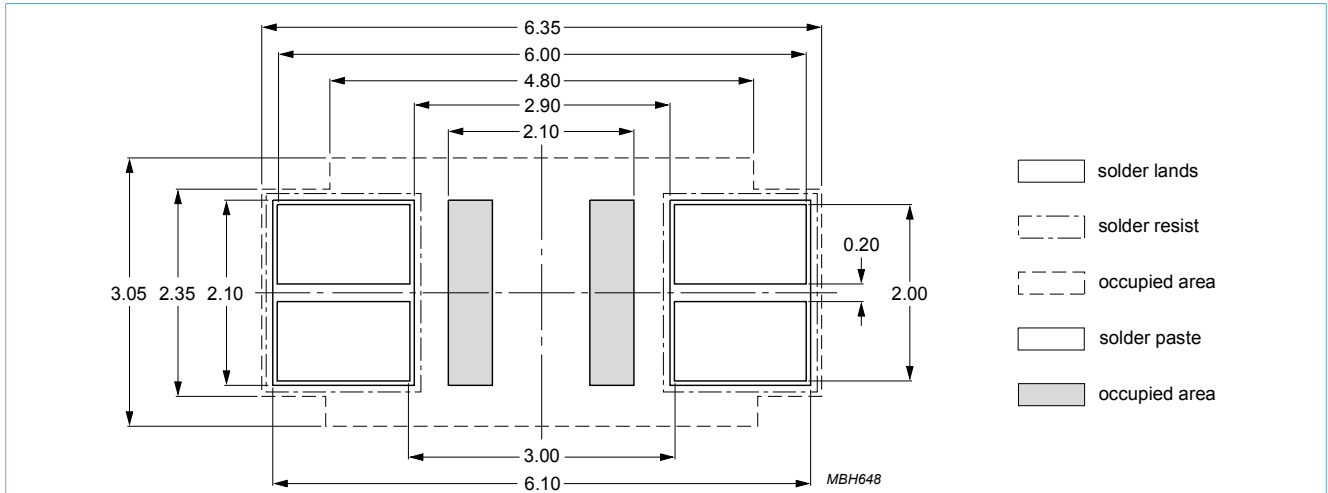


Fig. 2. Reflow soldering footprint for SMA; PMOS (SOD106)

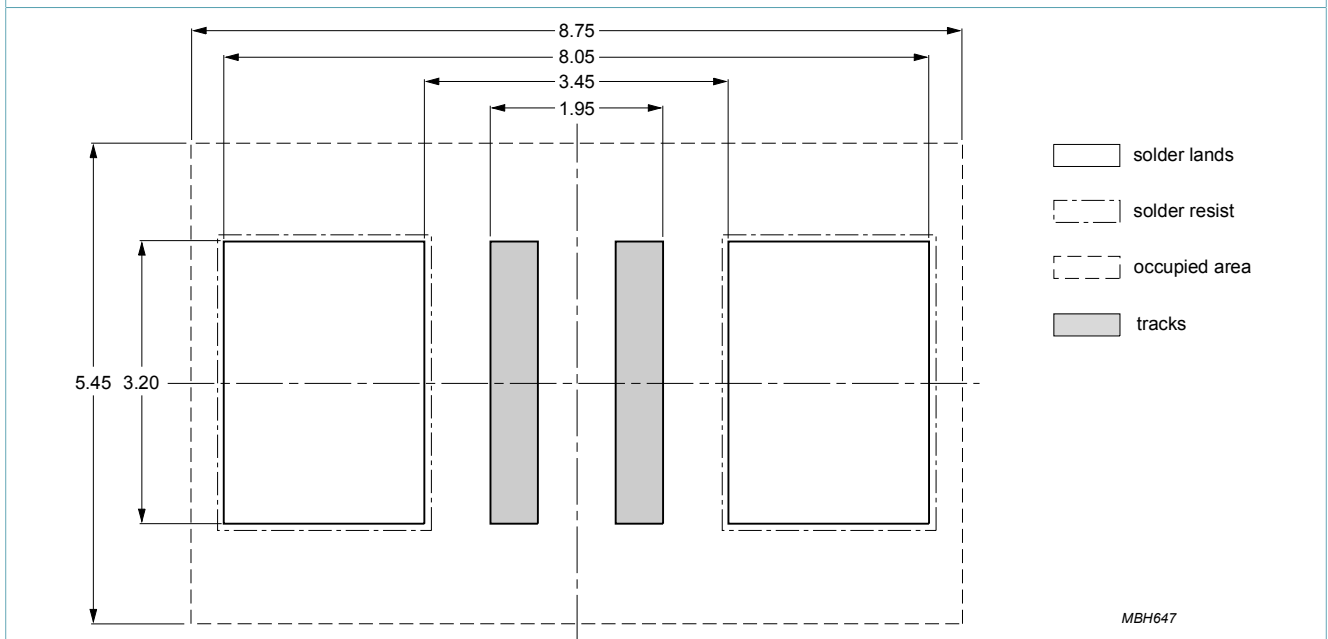


Fig. 3. Wave soldering footprint for SMA; PMOS (SOD106)

4. Legal information

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